

EDB003M06TM3, EDB003M06TM3L

Automotive 650 V, 3.3 mΩ, Silicon Carbide, Single Switch Power Module

V_{DS}	650 V
R_{DS(on)}	3.3 mΩ

Technical Features

- AQS 324 Qualified
- Very low On-State Resistance
- Baseplateless Module with High Performance Si₃N₄ Insulator
- Laser Weldable Power Terminals
- Sinterable and Solderable Backside (Silver Plated)
- Solderable Signal Pins (Silver Plated)
- Package with Extended Creepage
- Comparative Tracking Index (CTI) > 600 (Material Group I)
- Limited Extended Operation (T_{VJ(op)} = 200 °C for 100 h)



Typical Applications

- Automotive Traction Inverters

System Benefits

- Ultra-Low Loss
- High Performance in a small Footprint
- Design Flexibility
- Enables high Reliability Interconnects

Maximum Parameters (Verified by Design)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions	Note
Drain-Source Voltage	V _{DS}			650	V		
Gate-Source Voltage, Maximum Value	V _{GS(max)}	-8		+19		Transient	Note 1 Fig. 27
Gate-Source Voltage, Recommended	V _{GS(op)}		-4/+15			Static	
DC Continuous Drain Current	I _D		440		A	V _{GS} = 15 V, T _C = 100 °C, T _{VJ} = 175 °C	Note 2
Virtual Junction Temperature	T _{VJ(op)}	-40		175		Continuous operation	
				200		100 hours over lifetime	
Sinter Temperature	T _L		230		°C		
Sinter Pressure	P _s		14				

Note (1): Recommended turn-on gate voltage is 15 V with $\pm 5\%$ regulation tolerance

Note (2): Current limit calculated by $I_{D(max)} = \sqrt{(P_D / R_{DS(typ)})(T_{VJ(max)})}$ where $P_D = (T_{VJ} - T_C) / R_{th(JC,typ)}$


MOSFET Characteristics ($T_{VJ} = 25^\circ\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions	Note
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	650			V	$V_{GS} = 0 \text{ V}, T_{VJ} = -40^\circ\text{C}$	Fig. 10
Gate Threshold Voltage	$V_{GS(\text{th})}$	1.8	2.5	3.6		$V_{DS} = V_{GS}, I_D = 60 \text{ mA}$	
			2.0			$V_{DS} = V_{GS}, I_D = 60 \text{ mA}, T_{VJ} = 175^\circ\text{C}$	
Zero Gate Voltage Drain Current	I_{DSS}		4	200	μA	$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V}$	
Gate-Source Leakage Current	I_{GSS}		40	1000	nA	$V_{GS} = 15 \text{ V}, V_{DS} = 0 \text{ V}$	
Drain-Source On-State Resistance (Devices Only)	$R_{DS(\text{on})}$		3.3	4.1	$\text{m}\Omega$	$V_{GS} = 15 \text{ V}, I_D = 320 \text{ A}$	Note 3 Figs. 2, 3
			4.6	5.9		$V_{GS} = 15 \text{ V}, I_D = 320 \text{ A}, T_{VJ} = 175^\circ\text{C}$	
			5.1			$V_{GS} = 15 \text{ V}, I_D = 320 \text{ A}, T_{VJ} = 200^\circ\text{C}$	
Transconductance	g_{fs}		270		S	$V_{DS} = 20 \text{ V}, I_D = 320 \text{ A}$	Fig. 4
			255			$V_{DS} = 20 \text{ V}, I_D = 320 \text{ A}, T_{VJ} = 175^\circ\text{C}$	
Turn-On Switching Energy	E_{ON}		7.4		mJ	$T_{VJ} = 25^\circ\text{C}$	Figs. 11, 12, 13, 24, 25
			7.1			$T_{VJ} = 175^\circ\text{C}$	
			7.2			$T_{VJ} = 200^\circ\text{C}$	
Turn-Off Switching Energy	E_{OFF}		3.9			$T_{VJ} = 25^\circ\text{C}$	
			4.4			$T_{VJ} = 175^\circ\text{C}$	
			4.4			$T_{VJ} = 200^\circ\text{C}$	
Internal Gate Resistance	$R_{G(\text{int})}$		2.0		Ω	$f = 100 \text{ kHz}, V_{AC} = 250 \text{ mV}$	
Input Capacitance	C_{iss}		22.7		nF	$V_{GS} = 0 \text{ V}, V_{DS} = 400 \text{ V}, V_{AC} = 250 \text{ mV}, f = 100 \text{ kHz}$	Fig. 9
Output Capacitance	C_{oss}		1.18				
Reverse Transfer Capacitance	C_{rss}		104		PF		
Gate to Source Charge	Q_{GS}		240		nC	$V_{DS} = 400 \text{ V}, V_{GS} = -4 \text{ V}/15 \text{ V}, I_D = 320 \text{ A}, \text{per IEC60747-8-4}$	
Gate to Drain Charge	Q_{GD}		232				
Total Gate Charge	Q_G		832				
Thermal Resistance, Junction to Case	$R_{th(JC)}$		0.08		K/W		Fig. 16

Note (3): Total effective resistance = MOSFET $R_{DS(\text{on})}$ + package resistance



Diode Characteristics ($T_{vj} = 25^\circ\text{C}$ Unless Otherwise Specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions		Note
Body Diode Forward Voltage (Devices Only)	V_{SD}		6.2		V	$V_{GS} = -4\text{ V}$, $I_{SD} = 320\text{ A}$		Fig. 7
			5.7			$V_{GS} = -4\text{ V}$, $I_{SD} = 320\text{ A}$, $T_{vj} = 175^\circ\text{C}$		
Reverse Recovery Time	t_{RR}		32		ns	$V_{GS} = -4\text{ V}$, $I_{SD} = 325\text{ A}$, $V_R = 400\text{ V}$, $di/dt = 6.7\text{ A/ns}$, $T_{vj} = 175^\circ\text{C}$		Fig. 26
Reverse Recovery Charge	Q_{RR}		2.1		μC			
Peak Reverse Recovery Current	I_{RRM}		108		A			
Reverse Recovery Energy	E_{RR}		0.2		mJ	$T_{vj} = 25^\circ\text{C}$	$V_{DS} = 400\text{ V}$, $I_D = 325\text{ A}$, $V_{GS} = -4\text{ V}/15\text{ V}$, $R_{G(ON)} = 3\Omega$, $L_\sigma = 18.3\text{ nH}$	Figs. 11, 12, 13, 14, 26
			0.3			$T_{vj} = 175^\circ\text{C}$		
			0.3			$T_{vj} = 200^\circ\text{C}$		

Module Physical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions		Note	
Package Resistance	R_{pkg}		0.15		m Ω	$T_c = 25^\circ\text{C}$	Drain to power-source	Note 3	
			0.25			$T_c = 175^\circ\text{C}$			
Stray Inductance	L_{stray}		5.1		nH	Drain to power-source, $f = 10\text{ MHz}$			
Storage Temperature	T_{stg}	-40		125	°C				
Weight	W		8.6		g				
Case Isolation Voltage	V_{isol}	4.3			kV	DC, $t = 1\text{ s}$			
Comparative Tracking Index	CTI	600							
Creepage Distance		6.3			mm	Terminal to thermal pad			

Note (3): Total effective resistance = MOSFET $R_{DS(on)}$ + package resistance

Typical Performance

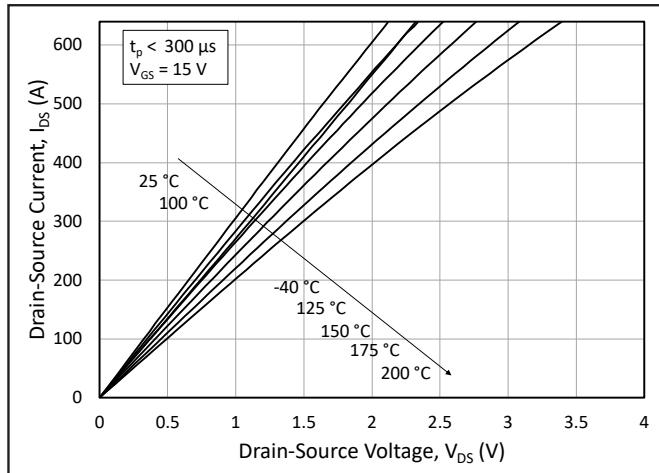


Figure 1. Output Characteristics for Various Junction Temperatures

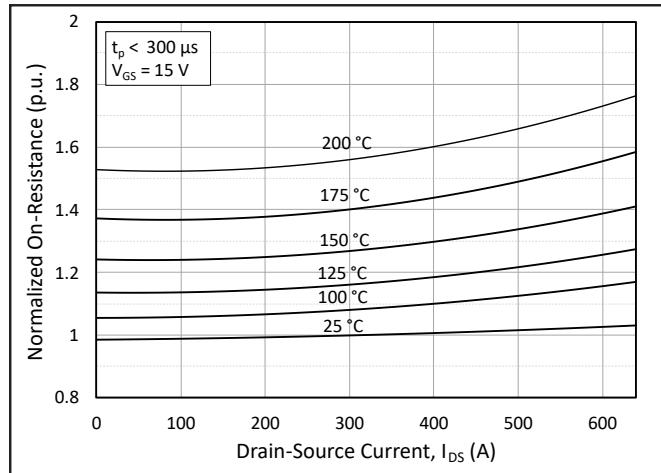


Figure 2. Normalized On-State Resistance vs. Drain Current for Various Junction Temperatures

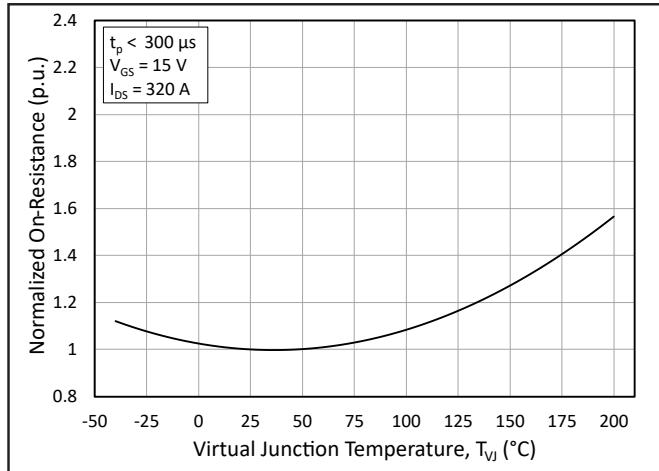


Figure 3. Normalized On-State Resistance vs. Junction Temperature

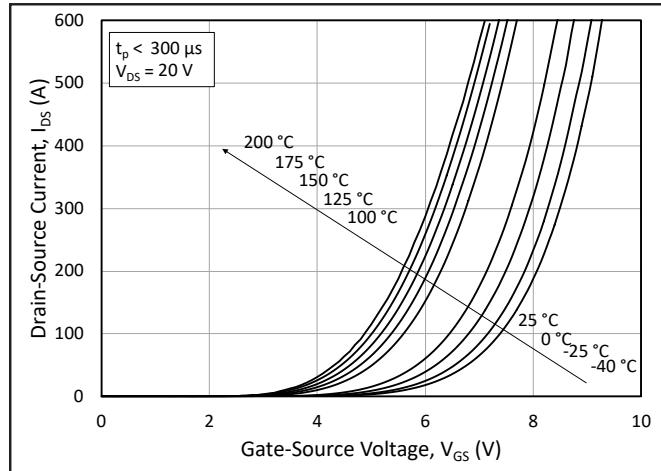


Figure 4. Transfer Characteristic for Various Junction Temperatures

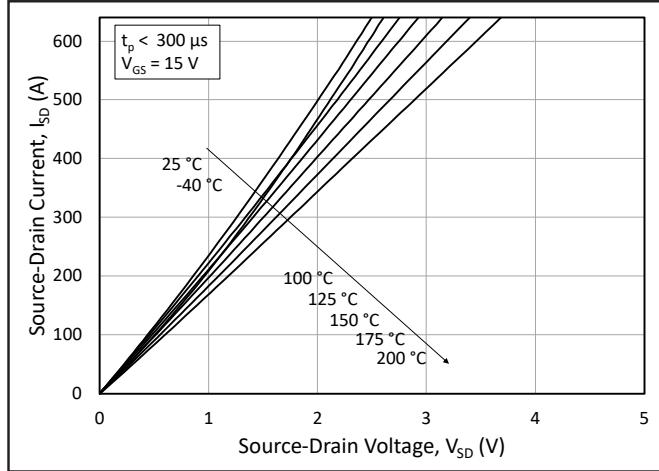


Figure 5. 3rd Quadrant Characteristic vs. Junction Temperatures at $V_{GS} = 15$ V

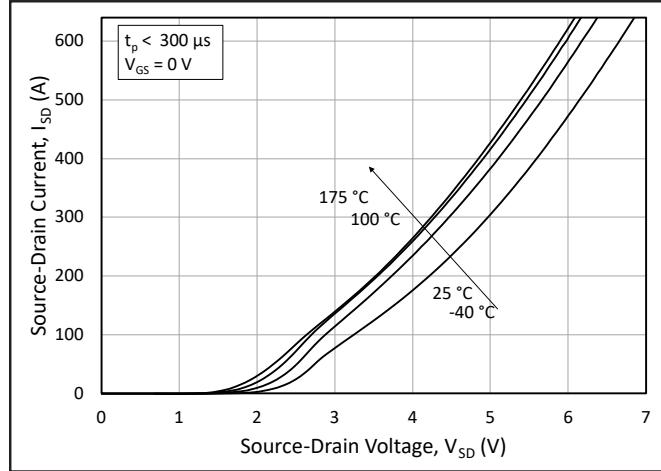


Figure 6. 3rd Quadrant Characteristic vs. Junction Temperatures at $V_{GS} = 0$ V (Body Diode)

Typical Performance

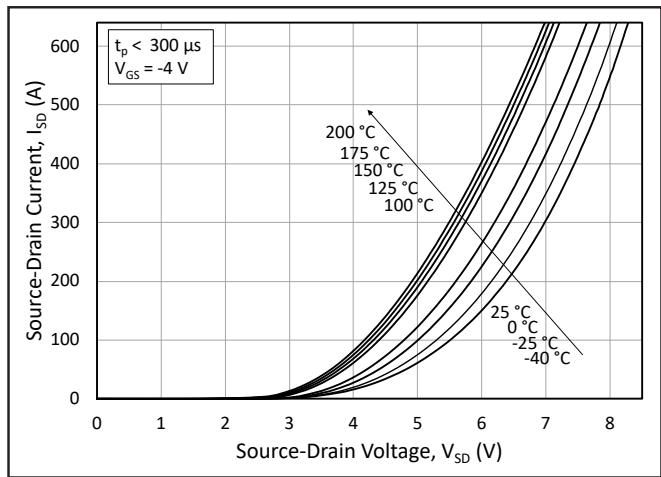


Figure 7. 3rd Quadrant Characteristic vs. Junction Temperature at $V_{GS} = -4 \text{ V}$ (Body Diode)

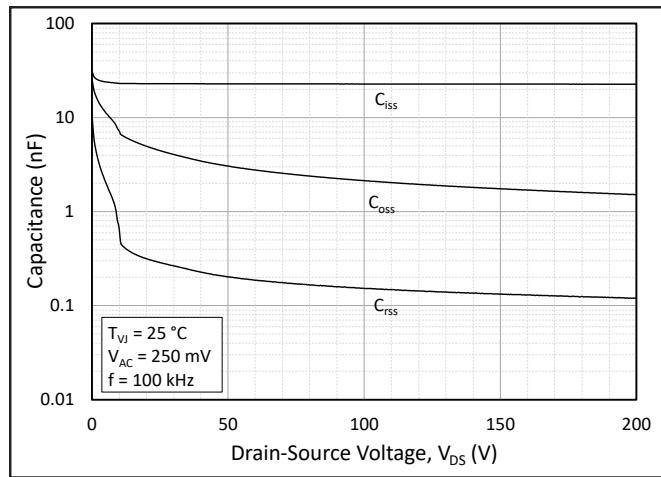


Figure 8. Typical Capacitances vs. Drain to Source Voltage (0 - 200 V)

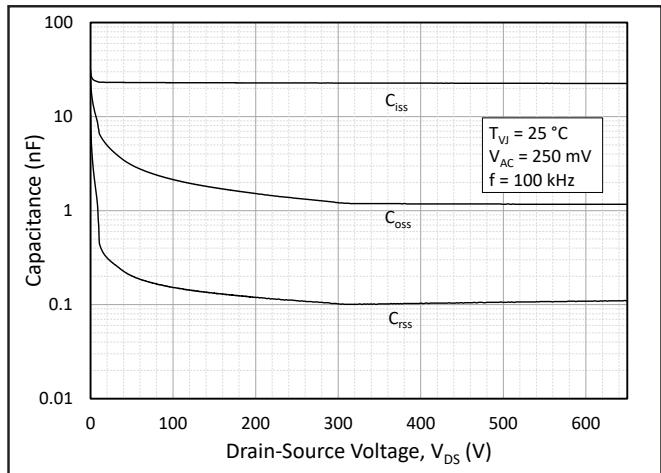


Figure 9. Typical Capacitances vs. Drain to Source Voltage (0 - 650V)

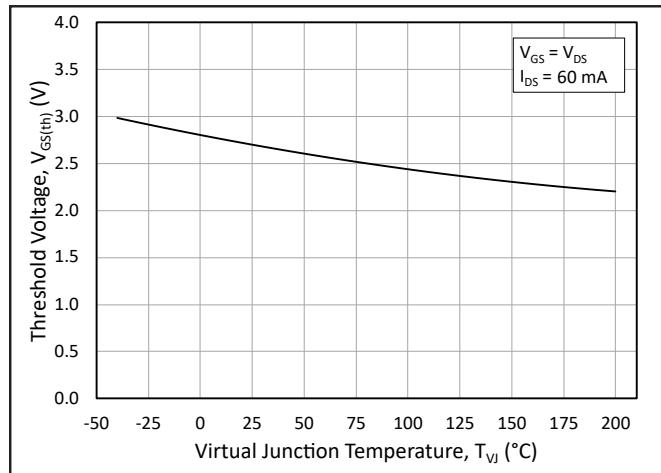


Figure 10. Threshold Voltage vs. Junction Temperature

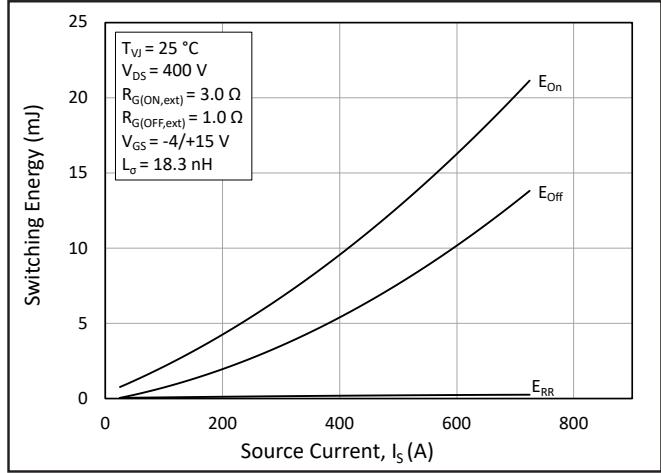


Figure 11. Switching Energy vs. Drain Current ($T_{VJ} = 25 \text{ }^{\circ}\text{C}$)

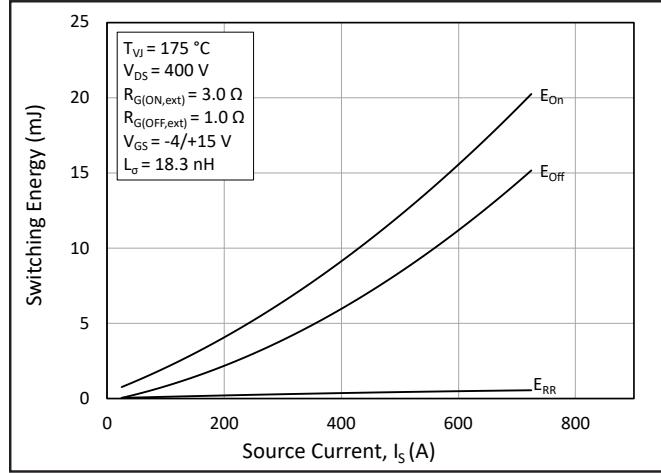
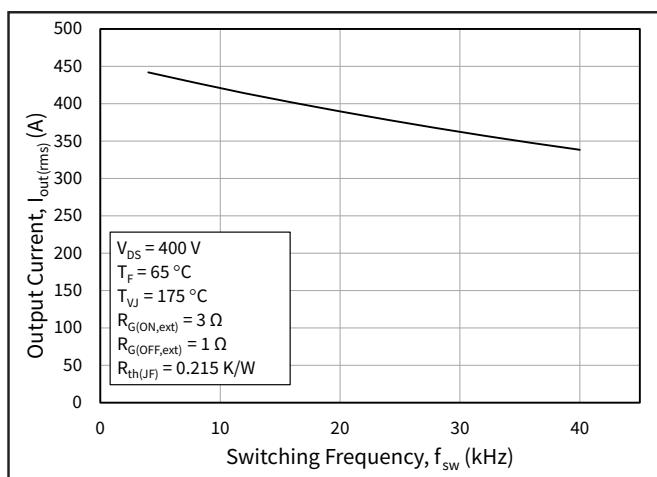
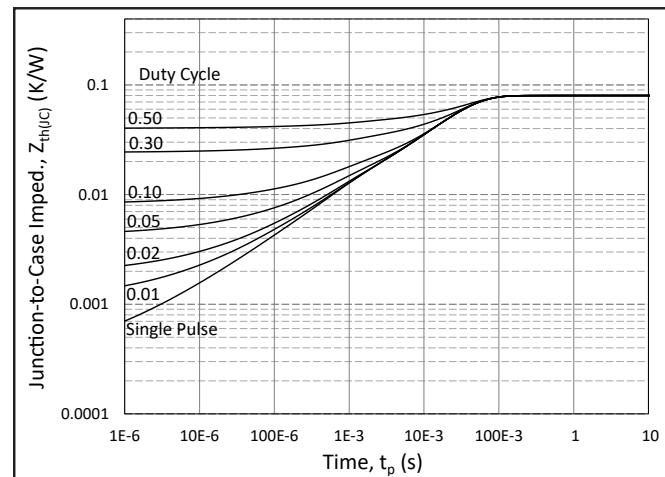
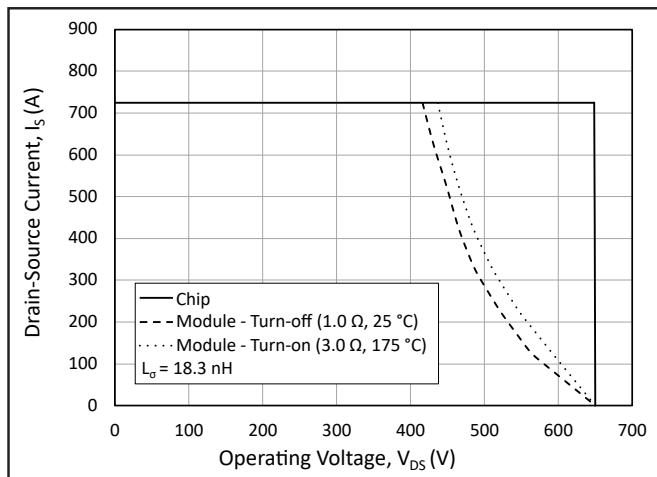
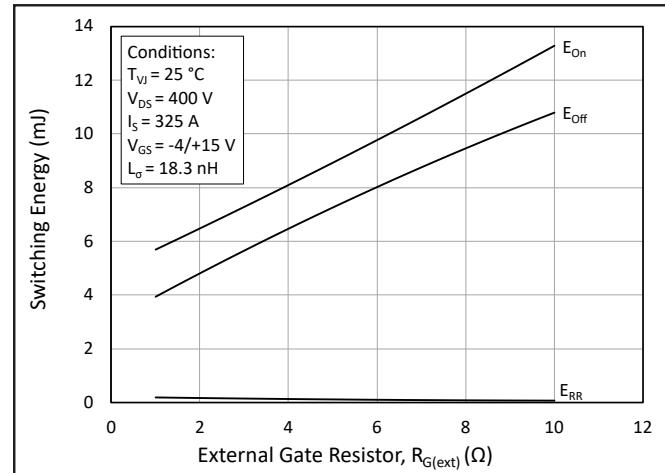
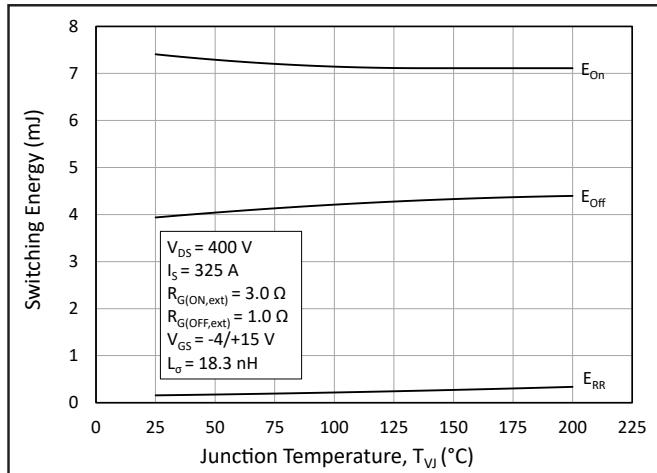


Figure 12. Switching Energy vs. Drain Current ($T_{VJ} = 175 \text{ }^{\circ}\text{C}$)

Typical Performance



Timing Characteristics

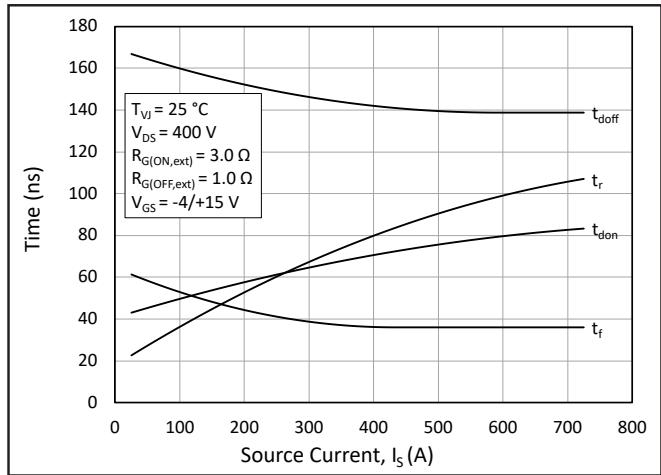


Figure 18. Timing vs. Source Current

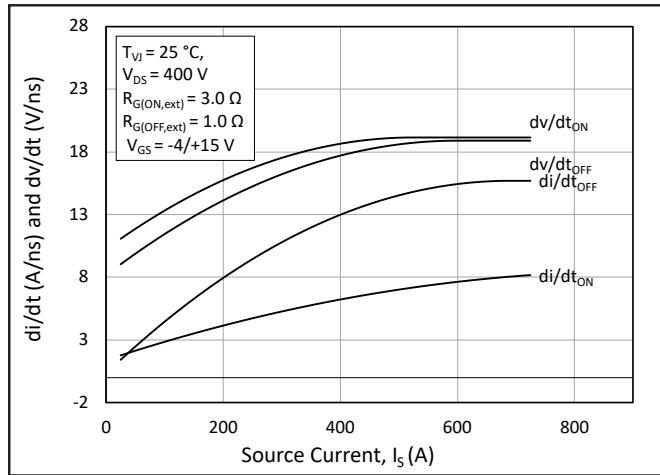


Figure 19. dv/dt and di/dt vs. Source Current

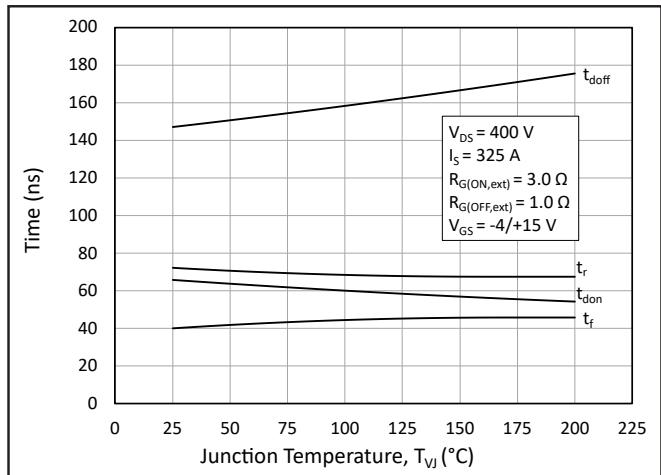


Figure 20. Timing vs. Junction Temperature

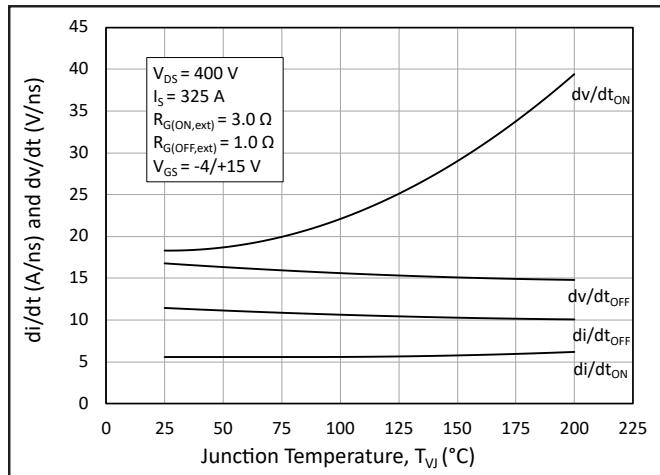


Figure 21. dv/dt and di/dt vs. Junction Temperature

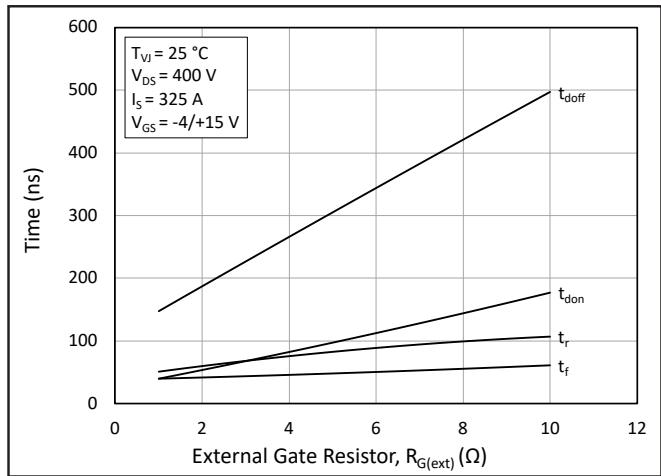


Figure 22. Timing vs. External Gate Resistance

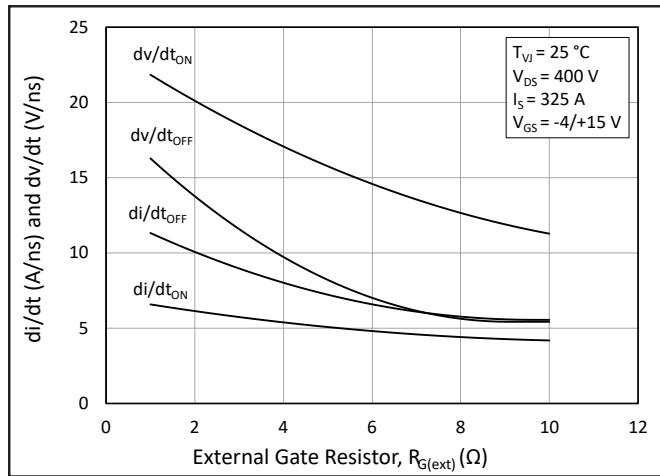


Figure 23. dv/dt and di/dt vs. External Gate Resistance

Definitions

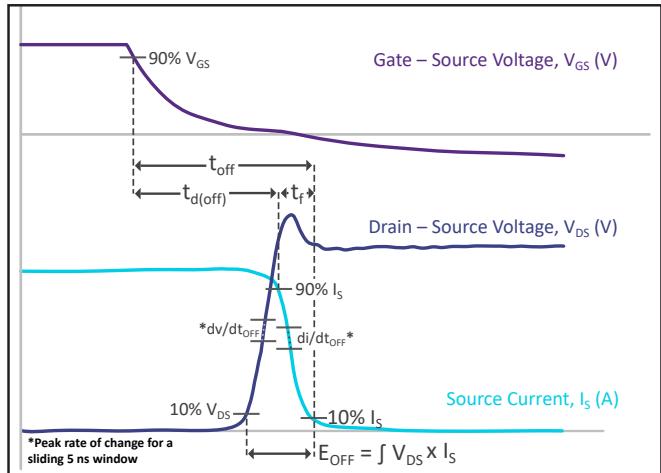


Figure 24. Turn-Off Transient Definitions

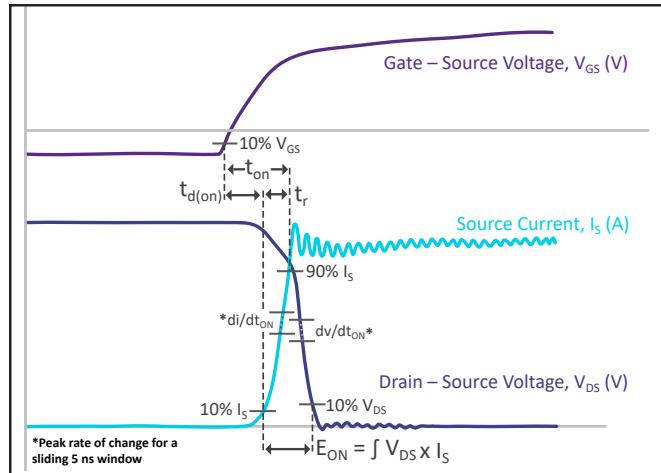


Figure 25. Turn-On Transient Definitions

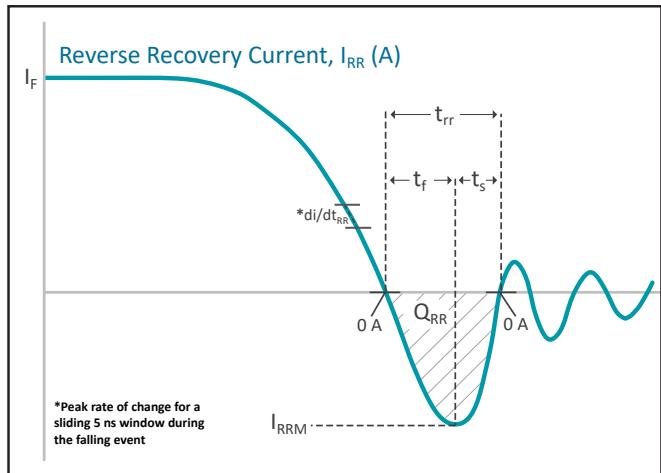


Figure 26. Reverse Recovery Definitions

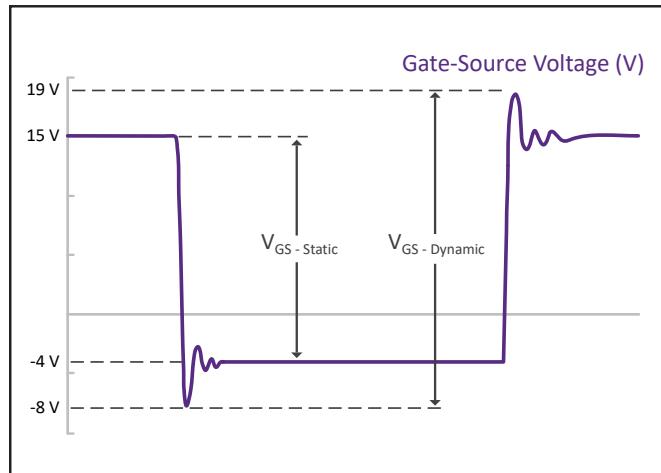
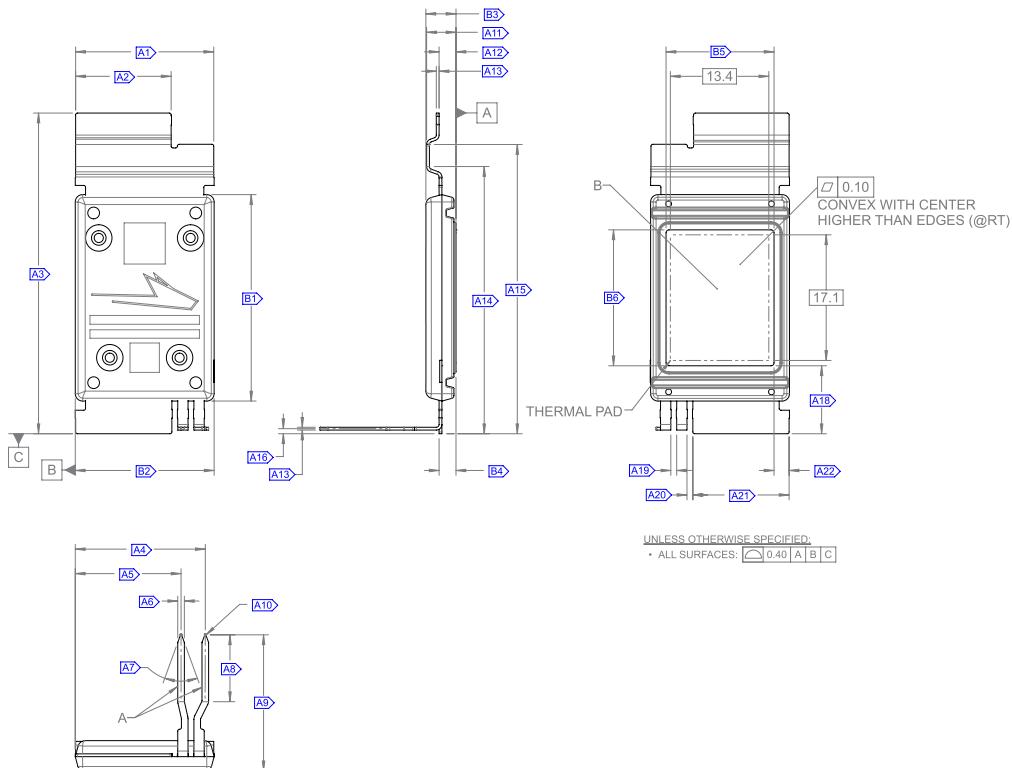


Figure 27. V_{GS} Transient Definitions

Schematic and Pin Out**Package Dimensions (mm)**

DIMENSION TABLE	
SYM.	DIMENSION/TOLERANCE
A1	18.8±0.20
A2	13±0.20
A3	43.65±0.30
B1	28.1±0.20
B2	18.9±0.30
A4	17.7±0.40
A5	14.4±0.40
B3	2±0.9±0.10
A6	2× [40°] [9.1] - Short pin version 9.6 - Long pin version
A7	18.5±0.50 - Short pin version 19.0±0.50 - Long pin version
A8	2× R0.1±0.10
B4	4.1±0.10
A9	4±0.30
A10	2.3±0.30
A11	[0.387]
A12	36.37±0.30
A13	39.37±0.30
A14	0.69±0.65
B5	2.3±0.30
B6	[14.7]
A15	[18.5]
A16	9.5 MAX
A17	[0.8]
A18	[0.8]
A19	13.1±0.20
A20	2.3 MAX

NOTE	
A	Ag Plating, Signal Pins
B	Ag Plating, Thermal Pad



Product Ordering Code

Part Number	Description
EDB003M06TM3	Short gate and Kelvin-source pin length
EDB003M06TM3L	Long gate and Kelvin-source pin length

Revision History

Revision History	Date	Brief Summary
Rev. 1	October 2025	Initial release
Rev. 2	December 2025	Updated drawing

Supporting Links & Tools

Evaluation Tools & Support

- [PLECS Circuit Model](#)
- 3D CAD Model
- FEA Thermal Model - Available Upon Request
- KIT-CRD-CIL-12N-TMA: Dynamic Performance Evaluation Kit for TM Power Modules

Application Notes

- [PRD-04814: Design Options for Wolfspeed® Silicon Carbide MOSFET Gate Bias Power Supplies](#)
- [PRD-06379: Environmental Considerations for Power Electronics Systems](#)
- [PRD-08333: Wolfspeed Module CIL Evaluation Kits User Guide](#)
- [PRD-08376: Thermal Characterization Methods and Applications](#)
- [PRD-08710: Measuring Stray Inductance in Power Electronics Systems](#)
- [PRD-08911: Considerations for Current Balancing in Paralleled SiC Power Modules](#)

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Contact info:

4600 Silicon Drive
Durham, NC 27703 USA
Tel: +1.919.313.5300
www.wolfspeed.com/power